

# MATERIAL DECLARATION SHEET



Material	MF-USML Series
Product Line	Multifuse
Revision Date	Oct. 2, 2017
Revision	D
RoHS Compliant	Yes
Halogen Free Compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)		
1	Metal Carbide	Titanium Carbide	0.0105332	12070-08-5	44.774%	44.774%	44.7747%	
2	Copper Plating	Copper	0.0016969	7440-50-8	7.213%	7.213%	7.2132%	
3	Foil	Copper	0.0047480	7440-50-8	20.183%	21.245%	20.1830%	
		Nickel	0.0002499	7440-02-0	1.062%		1.0623%	
4	PCB Foil	Copper	0.0024990	7440-50-8	10.623%	10.623%	10.6226%	
5	Polymer	Polyethylene Homopolymer	0.0008264	9002-88-4	3.513%	3.518%	3.5129%	
		Proprietary Additives	0.0000012	-	0.005%		0.0051%	
6	Prepreg	Epoxy	0.0019160	35948-25-5	8.145%	12.461%	8.1448%	
		Glass fiber	0.0010153	65997-17-3	4.316%		4.3160%	
7	Solder Plating	Nickel	0.0000385	7440-02-0	0.164%	0.166%	0.1637%	
		Gold	0.0000004	7440-57-5	0.002%		0.0018%	
		Total Weight (%)						
			Total weight (grams)	0.0235249	Total	100%	100%	100.00%